

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>DUO HUI BEI</td> <td>01/07/2011</td> </tr> <tr> <td>MING YUAN LIU</td> <td>01/10/2011</td> </tr> <tr> <td>CHUN SHENG ZHENG</td> <td>01/07/2011</td> </tr> </tbody> </table>		Name	Execution Date	DUO HUI BEI	01/07/2011	MING YUAN LIU	01/10/2011	CHUN SHENG ZHENG	01/07/2011		
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RECEIVING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Semiconductor Manufacturing International (Shanghai) Corporation</td> </tr> <tr> <td>Street Address:</td> <td>18 Zhang Jiang Road, Pudong New Area</td> </tr> <tr> <td>City:</td> <td>Shanghai</td> </tr> <tr> <td>State/Country:</td> <td>CHINA</td> </tr> <tr> <td>Postal Code:</td> <td>201203</td> </tr> </table>		Name:	Semiconductor Manufacturing International (Shanghai) Corporation	Street Address:	18 Zhang Jiang Road, Pudong New Area	City:	Shanghai	State/Country:	CHINA	Postal Code:	201203
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
Fax Number: (650)326-2422 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 415-576-0200 Email: jbsalvador@townsend.com Correspondent Name: KILPATRICK TOWNSEND & STOCKTON LLP Address Line 1: Two Embarcadero Center, Eighth Floor Address Line 4: San Francisco, CALIFORNIA 94111-3834											
ATTORNEY DOCKET NUMBER:	021653-020100US										
NAME OF SUBMITTER:	Dah-Bin Kao										
Total Attachments: 3 source=021653-020100US SIGNED ASSIGNMENT BY INVENTORS#page1.tif source=021653-020100US SIGNED ASSIGNMENT BY INVENTORS#page2.tif											

CH \$40.00 12938158

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PATENT
REEL: 025611 FRAME: 0386

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, DUO HUI BEI of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China; MING YUAN LIU of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China; and CHUN SHENG ZHENG of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: METHOD FOR COPPER HILLOCK REDUCTION

Date(s) of execution of Declaration:

Filing Date: November 2, 2010

Application No.: 12/938,158; and

WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd, Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignor, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: Jan. 7, 2011

Duo Hui Bei
DUO HUI BEI

Dated: _____

MING YUAN LIU
MING YUAN LIU

Dated: _____

CHUN SHENG ZHENG
CHUN SHENG ZHENG

63079635 v1

ASSIGNMENT OF PATENT APPLICATION

JOINT

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IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: _____

DUO HUI BEI

Dated: 2011/1/10

MING YUAN LIU

Dated: _____

CHUN SHENG ZHENG

63079633.v1

ASSIGNMENT OF PATENT APPLICATION

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Dated: _____

DUO HUI BEI

Dated: _____

MING YUAN LIU

Dated: 2011-01-07

CHUN SHENG ZHENG
CHUN SHENG ZHENG

63079635 v1